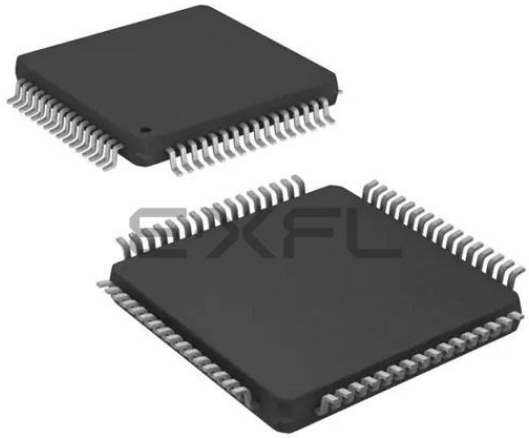

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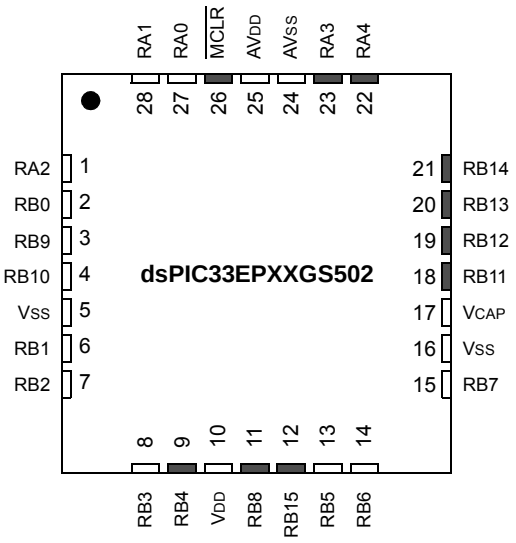
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	53
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 22x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep32gs506-e-pt

Pin Diagrams (Continued)

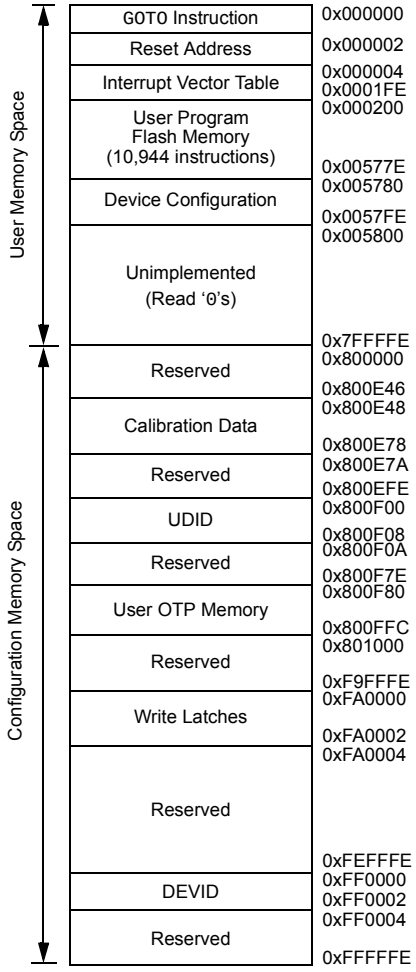
28-Pin QFN-S, UQFN



Pin	Pin Function	Pin	Pin Function
1	AN2/PGA1P3/PGA2P2/CMP1C/CMP2A/RA2	15	PGEC1/AN21/SDA1/**RP39**/RB7
2	AN3/PGA2P3/CMP1D/CMP2B/**RP32**/RB0	16	VSS
3	AN4/CMP2C/CMP3A/ISRC4/**RP41**/RB9	17	VCAP
4	AN5/CMP2D/CMP3B/ISRC3/**RP42**/RB10	18	TMS/PWM3H/**RP43**/RB11
5	Vss	19	TCK/PWM3L/**RP44**/**R**B12
6	OSC1/CLKI/AN6/CMP3C/CMP4A/ISRC2/**RP33**/RB1	20	PWM2H/**RP45**/RB13
7	OSC2/CLKO/AN7/PGA1N2/CMP3D/CMP4B/**RP34**/RB2	21	PWM2L/**RP46**/RB14
8	PGED2/AN18/DACOUT1/INT0/**RP35**/RB3	22	PWM1H/RA4
9	PGEC2/ADTRG31/EXTREF1/RP36/RB4	23	PWM1L/RA3
10	VDD	24	AVSS
11	PGED3/SDA2/FLT31/RP40/RB8	25	AVDD
12	PGEC3/SCL2/**RP47**/RB15	26	$\overline{\text{MCLR}}$
13	TDO/AN19/PGA2N2/**RP37**/RB5	27	AN0/PGA1P1/CMP1A/RA0
14	PGED1/TDI/AN20/SCL1/**RP38**/RB6	28	AN1/PGA1P2/PGA2P1/CMP1B/RA1

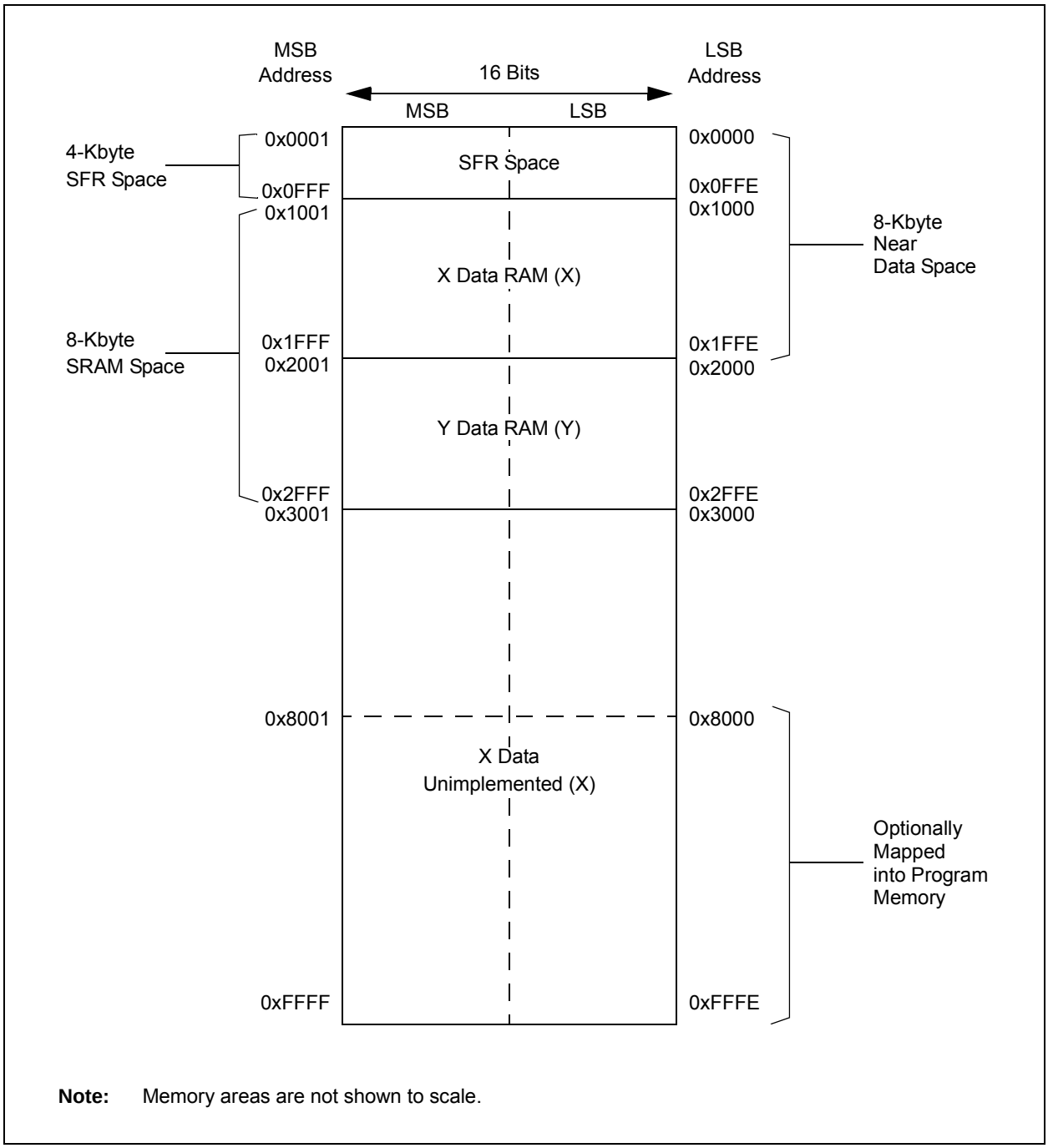
Legend: **Shaded pins** are up to 5 VDC tolerant.
RPn represents remappable peripheral functions. See Table 10-1 and Table 10-2 for the complete list of remappable sources.

FIGURE 4-2: PROGRAM MEMORY MAP FOR dsPIC33EP32GS50X DEVICES



Note: Memory areas are not shown to scale.

FIGURE 4-8: DATA MEMORY MAP FOR dsPIC33EP64GS50X DEVICES



Note: Memory areas are not shown to scale.

TABLE 4-4: TIMER1 THROUGH TIMER5 REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TMR1	0100	Timer1 Register																xxxx
PR1	0102	Period Register 1																FFFF
T1CON	0104	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	TSYNC	TCS	—	0000
TMR2	0106	Timer2 Register																xxxx
TMR3HLD	0108	Timer3 Holding Register (for 32-bit timer operations only)																xxxx
TMR3	010A	Timer3 Register																xxxx
PR2	010C	Period Register 2																FFFF
PR3	010E	Period Register 3																FFFF
T2CON	0110	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	T32	—	TCS	—	0000
T3CON	0112	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	—	TCS	—	0000
TMR4	0114	Timer4 Register																xxxx
TMR5HLD	0116	Timer5 Holding Register (for 32-bit operations only)																xxxx
TMR5	0118	Timer5 Register																xxxx
PR4	011A	Period Register 4																FFFF
PR5	011C	Period Register 5																FFFF
T4CON	011E	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	T32	—	TCS	—	0000
T5CON	0120	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	—	TCS	—	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

5.6 Control Registers

Five SFRs are used to write and erase the program Flash memory: NVMCON, NVMKEY, NVMADR, NVMADRU and NVMSRCADR/H.

The NVMCON register (Register 5-1) selects the operation to be performed (page erase, word/row program, Inactive Partition erase), initiates the program or erase cycle and is used to determine the Active Partition in Dual Partition modes.

NVMKEY (Register 5-4) is a write-only register that is used for write protection. To start a programming or erase sequence, the user application must consecutively write 0x55 and 0xAA to the NVMKEY register.

There are two NVM Address registers: NVMADRU and NVMADR. These two registers, when concatenated, form the 24-bit Effective Address (EA) of the selected word/row for programming operations, or the selected page for erase operations. The NVMADRU register is used to hold the upper 8 bits of the EA, while the NVMADR register is used to hold the lower 16 bits of the EA.

For row programming operation, data to be written to program Flash memory is written into data memory space (RAM) at an address defined by the NVMSRCADR register (location of first element in row programming data).

REGISTER 6-1: RCON: RESET CONTROL REGISTER(1) (CONTINUED)

bit 3 **SLEEP:** Wake-up from Sleep Flag bit
1 = Device has been in Sleep mode
0 = Device has not been in Sleep mode

bit 2 **IDLE:** Wake-up from Idle Flag bit
1 = Device has been in Idle mode
0 = Device has not been in Idle mode

bit 1 **BOR:** Brown-out Reset Flag bit
1 = A Brown-out Reset has occurred
0 = A Brown-out Reset has not occurred

bit 0 **POR:** Power-on Reset Flag bit
1 = A Power-on Reset has occurred
0 = A Power-on Reset has not occurred

Note 1: All of the Reset status bits can be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

2: If the WDTEN<1:0> Configuration bits are '11' (unprogrammed), the WDT is always enabled, regardless of the SWDTEN bit setting.

REGISTER 7-3: INTCON1: INTERRUPT CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NSTDIS	OVAERR	OVBERR	COVAERR	COVBERR	OVATE	OVBTE	COVTE
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
SFTACERR	DIV0ERR	—	MATHERR	ADDRERR	STKERR	OSCFAIL	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **NSTDIS:** Interrupt Nesting Disable bit
1 = Interrupt nesting is disabled
0 = Interrupt nesting is enabled

bit 14 **OVAERR:** Accumulator A Overflow Trap Flag bit
1 = Trap was caused by overflow of Accumulator A
0 = Trap was not caused by overflow of Accumulator A

bit 13 **OVBERR:** Accumulator B Overflow Trap Flag bit
1 = Trap was caused by overflow of Accumulator B
0 = Trap was not caused by overflow of Accumulator B

bit 12 **COVAERR:** Accumulator A Catastrophic Overflow Trap Flag bit
1 = Trap was caused by catastrophic overflow of Accumulator A
0 = Trap was not caused by catastrophic overflow of Accumulator A

bit 11 **COVBERR:** Accumulator B Catastrophic Overflow Trap Flag bit
1 = Trap was caused by catastrophic overflow of Accumulator B
0 = Trap was not caused by catastrophic overflow of Accumulator B

bit 10 **OVATE:** Accumulator A Overflow Trap Enable bit
1 = Trap overflow of Accumulator A
0 = Trap is disabled

bit 9 **OVBTE:** Accumulator B Overflow Trap Enable bit
1 = Trap overflow of Accumulator B
0 = Trap is disabled

bit 8 **COVTE:** Catastrophic Overflow Trap Enable bit
1 = Trap on catastrophic overflow of Accumulator A or B is enabled
0 = Trap is disabled

bit 7 **SFTACERR:** Shift Accumulator Error Status bit
1 = Math error trap was caused by an invalid accumulator shift
0 = Math error trap was not caused by an invalid accumulator shift

bit 6 **DIV0ERR:** Divide-by-Zero Error Status bit
1 = Math error trap was caused by a divide-by-zero
0 = Math error trap was not caused by a divide-by-zero

bit 5 **Unimplemented:** Read as ‘0’

bit 4 **MATHERR:** Math Error Status bit
1 = Math error trap has occurred
0 = Math error trap has not occurred

bit 3 **ADDRERR:** Address Error Trap Status bit
1 = Address error trap has occurred
0 = Address error trap has not occurred

6. The Peripheral Pin Select (PPS) pin mapping rules are as follows:
   a) Only one “output” function can be active on a given pin at any time, regardless if it is a dedicated or remappable function (one pin, one output).
   b) It is possible to assign a “remappable output” function to multiple pins and externally short or tie them together for increased current drive.
   c) If any “dedicated output” function is enabled on a pin, it will take precedence over any remappable “output” function.
   d) If any “dedicated digital” (input or output) function is enabled on a pin, any number of “input” remappable functions can be mapped to the same pin.
   e) If any “dedicated analog” function(s) are enabled on a given pin, “digital input(s)” of any kind will all be disabled, although a single “digital output”, at the user’s cautionary discretion, can be enabled and active as long as there is no signal contention with an external analog input signal. For example, it is possible for the ADC to convert the digital output logic level, or to toggle a digital output on a comparator or ADC input, provided there is no external analog input, such as for a built-in self-test.
   f) Any number of “input” remappable functions can be mapped to the same pin(s) at the same time, including to any pin with a single output from either a dedicated or remappable “output”.
   g) The TRISx registers control *only* the digital I/O output buffer. Any other dedicated or remappable active “output” will automatically override the TRISx setting. The TRISx register *does not* control the digital logic “input” buffer. Remappable digital “inputs” do not automatically override TRISx settings, which means that the TRISx bit must be set to input for pins with only remappable input function(s) assigned.
   h) All analog pins are enabled by default after any Reset and the corresponding digital input buffer on the pin has been disabled. Only the Analog Pin Select x (ANSELx) registers control the digital input buffer, *not* the TRISx register. The user must disable the analog function on a pin using the Analog Pin Select x registers in order to use any “digital input(s)” on a corresponding pin, no exceptions.

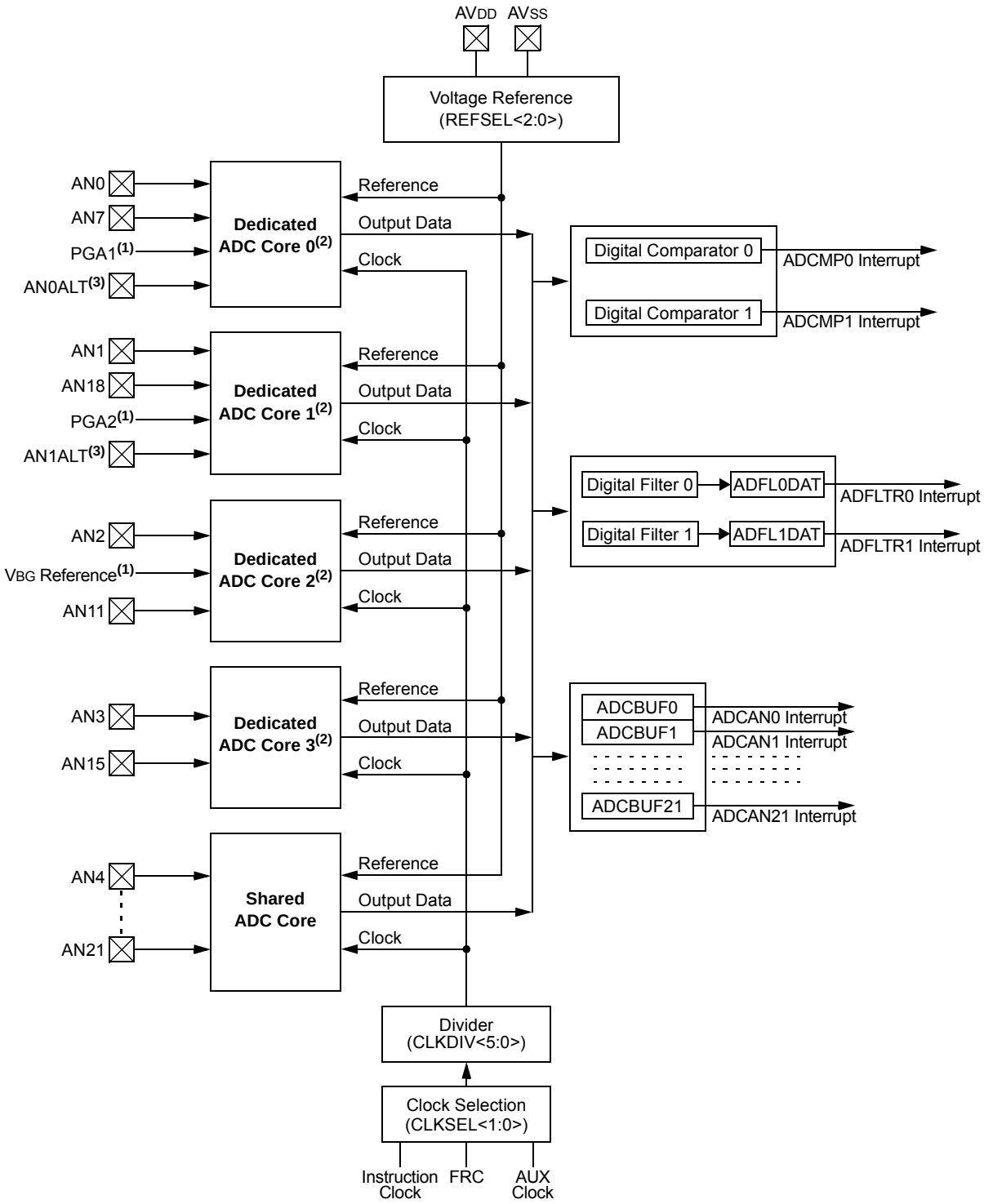
10.6 I/O Ports Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page contains the latest updates and additional information.

10.6.1 KEY RESOURCES

- **“I/O Ports”** (DS70000598) in the *“dsPIC33/PIC24 Family Reference Manual”*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *“dsPIC33/PIC24 Family Reference Manual”* Sections
- Development Tools

FIGURE 19-1: ADC MODULE BLOCK DIAGRAM



Note 1: PGA1, PGA2 and Band Gap Reference (V_{BG}) are internal analog inputs and are not available on device pins.
2: If the dedicated core uses an alternate channel, then shared core function cannot be used.
3: AN0ALT and AN1ALT are not available on dsPIC33EPXXGS502 devices.

REGISTER 19-3: ADCON2L: ADC CONTROL REGISTER 2 LOW

R/W-0	R/W-0	r-0	R/W-0	r-0	R/W-0	R/W-0	R/W-0
REFCIE	REFERCIE	—	EIEN	—	SHREISEL2(1)	SHREISEL1(1)	SHREISEL0(1)
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	SHRADCS6	SHRADCS5	SHRADCS4	SHRADCS3	SHRADCS2	SHRADCS1	SHRADCS0
bit 7							bit 0

Legend:	r = Reserved bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **REFCIE:** Band Gap and Reference Voltage Ready Common Interrupt Enable bit
1 = Common interrupt will be generated when the band gap will become ready
0 = Common interrupt is disabled for the band gap ready event

bit 14 **REFERCIE:** Band Gap or Reference Voltage Error Common Interrupt Enable bit
1 = Common interrupt will be generated when a band gap or reference voltage error is detected
0 = Common interrupt is disabled for the band gap and reference voltage error event

bit 13 **Reserved:** Maintain as '0'

bit 12 **EIEN:** Early Interrupts Enable bit
1 = The early interrupt feature is enabled for the input channel interrupts (when the EISTATx flag is set)
0 = The individual interrupts are generated when conversion is done (when the ANxRDY flag is set)

bit 11 **Reserved:** Maintain as '0'

bit 10-8 **SHREISEL<2:0>:** Shared Core Early Interrupt Time Selection bits(1)
111 = Early interrupt is set and interrupt is generated 8 TADCORE clocks prior to when the data is ready
110 = Early interrupt is set and interrupt is generated 7 TADCORE clocks prior to when the data is ready
101 = Early interrupt is set and interrupt is generated 6 TADCORE clocks prior to when the data is ready
100 = Early interrupt is set and interrupt is generated 5 TADCORE clocks prior to when the data is ready
011 = Early interrupt is set and interrupt is generated 4 TADCORE clocks prior to when the data is ready
010 = Early interrupt is set and interrupt is generated 3 TADCORE clocks prior to when the data is ready
001 = Early interrupt is set and interrupt is generated 2 TADCORE clocks prior to when the data is ready
000 = Early interrupt is set and interrupt is generated 1 TADCORE clock prior to when the data is ready

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **SHRADCS<6:0>:** Shared ADC Core Input Clock Divider bits
These bits determine the number of TCORESRC (Source Clock Periods) for one shared TADCORE (Core Clock Period).
1111111 = 254 Source Clock Periods
•
•
•
0000011 = 6 Source Clock Periods
0000010 = 4 Source Clock Periods
0000001 = 2 Source Clock Periods
0000000 = 2 Source Clock Periods

Note 1: For the 6-bit shared ADC core resolution (SHRRES<1:0> = 00), the SHREISEL<2:0> settings, from '100' to '111', are not valid and should not be used. For the 8-bit shared ADC core resolution (SHRRES<1:0> = 01), the SHREISEL<2:0> settings, '110' and '111', are not valid and should not be used.

REGISTER 19-28: ADCAL0L: ADC CALIBRATION REGISTER 0 LOW

R-0, HSC	U-0	U-0	U-0	r-0	R/W-0	R/W-0	R/W-0
CAL1RDY	—	—	—	—	CAL1DIFF	CAL1EN	CAL1RUN
bit 15							bit 8

R-0, HSC	U-0	U-0	U-0	r-0	R/W-0	R/W-0	R/W-0
CAL0RDY	—	—	—	—	CAL0DIFF	CAL0EN	CAL0RUN
bit 7							bit 0

Legend:	r = Reserved bit	U = Unimplemented bit, read as '0'	
R = Readable bit	W = Writable bit	HSC = Hardware Settable/Clearable bit	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CAL1RDY:** Dedicated ADC Core 1 Calibration Status Flag bit
1 = Dedicated ADC Core 1 calibration is finished
0 = Dedicated ADC Core 1 calibration is in progress

bit 14-12 **Unimplemented:** Read as '0'

bit 11 **Reserved:** Must be written as '0'

bit 10 **CAL1DIFF:** Dedicated ADC Core 1 Differential-Mode Calibration bit
1 = Dedicated ADC Core 1 will be calibrated in Differential Input mode
0 = Dedicated ADC Core 1 will be calibrated in Single-Ended Input mode

bit 9 **CAL1EN:** Dedicated ADC Core 1 Calibration Enable bit
1 = Dedicated ADC Core 1 calibration bits (CALxRDY, CALxDIFF and CALxRUN) can be accessed by software
0 = Dedicated ADC Core 1 calibration bits are disabled

bit 8 **CAL1RUN:** Dedicated ADC Core 1 Calibration Start bit
1 = If this bit is set by software, the dedicated ADC Core 1 calibration cycle is started; this bit is automatically cleared by hardware
0 = Software can start the next calibration cycle

bit 7 **CAL0RDY:** Dedicated ADC Core 0 Calibration Status Flag bit
1 = Dedicated ADC Core 0 calibration is finished
0 = Dedicated ADC Core 0 calibration is in progress

bit 6-4 **Unimplemented:** Read as '0'

bit 3 **Reserved:** Must be written as '0'

bit 2 **CAL0DIFF:** Dedicated ADC Core 0 Differential-Mode Calibration bit
1 = Dedicated ADC Core 0 will be calibrated in Differential Input mode
0 = Dedicated ADC Core 0 will be calibrated in Single-Ended Input mode

bit 1 **CAL0EN:** Dedicated ADC Core 0 Calibration Enable bit
1 = Dedicated ADC Core 0 calibration bits (CALxRDY, CALxDIFF and CALxRUN) can be accessed by software
0 = Dedicated ADC Core 0 calibration bits are disabled

bit 0 **CAL0RUN:** Dedicated ADC Core 0 Calibration Start bit
1 = If this bit is set by software, the dedicated ADC Core 0 calibration cycle is started; this bit is automatically cleared by hardware
0 = Software can start the next calibration cycle

21.0 PROGRAMMABLE GAIN AMPLIFIER (PGA)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXGS50X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Programmable Gain Amplifier (PGA)"** (DS70005146) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

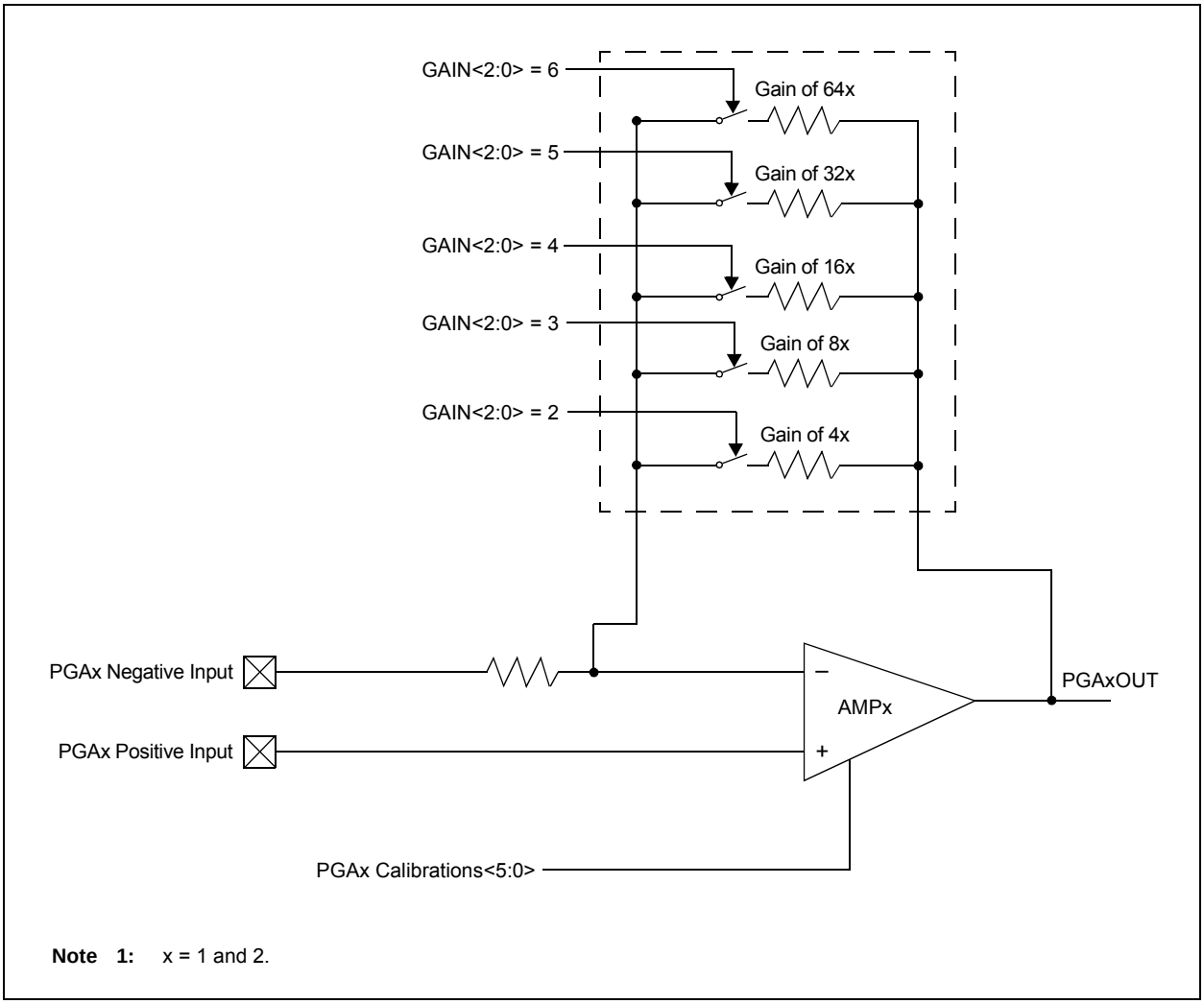
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXGS50X family devices have two Programmable Gain Amplifiers (PGA1, PGA2). The PGA is an op amp-based, non-inverting amplifier with user-programmable gains. The output of the PGA can be connected to a number of dedicated Sample-and-Hold inputs of the Analog-to-Digital Converter and/or to the high-speed analog comparator module. The PGA has five selectable gains and may be used as a ground referenced amplifier (single-ended) or used with an independent ground reference point.

Key features of the PGA module include:

- Single-Ended or Independent Ground Reference
- Selectable Gains: 4x, 8x, 16x, 32x and 64x
- High Gain Bandwidth
- Rail-to-Rail Output Voltage
- Wide Input Voltage Range

FIGURE 21-1: PGAx MODULE BLOCK DIAGRAM



Note 1: x = 1 and 2.

23.3 User OTP Memory

dsPIC33EPXXGS50X family devices contain 64 words of User One-Time-Programmable (OTP) memory, located at addresses, 0x800F80 through 0x800FFE. The User OTP Words can be used for storing checksum, code revisions, product information, such as serial numbers, system manufacturing dates, manufacturing lot numbers and other application-specific information. These words can only be written once at program time and not at run time; they can be read at run time.

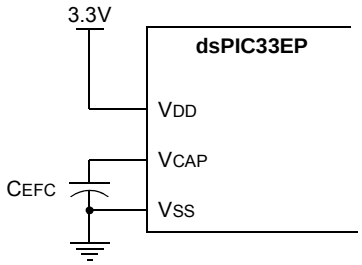
23.4 On-Chip Voltage Regulator

All the dsPIC33EPXXGS50X family devices power their core digital logic at a nominal 1.8V. This can create a conflict for designs that are required to operate at a higher typical voltage, such as 3.3V. To simplify system design, all devices in the dsPIC33EPXXGS50X family incorporate an on-chip regulator that allows the device to run its core logic from VDD.

The regulator provides power to the core from the other VDD pins. A low-ESR (less than 1 Ohm) capacitor (such as tantalum or ceramic) must be connected to the VCAP pin (Figure 23-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in Table 26-5, located in **Section 26.0 "Electrical Characteristics"**.

Note:	It is important for the low-ESR capacitor to be placed as close as possible to the VCAP pin.

FIGURE 23-1: CONNECTIONS FOR THE ON-CHIP VOLTAGE REGULATOR(1,2,3)



Note 1: These are typical operating voltages. Refer to Table 26-5 located in **Section 26.0 "Electrical Characteristics"** for the full operating ranges of VDD and VCAP.

2: It is important for the low-ESR capacitor to be placed as close as possible to the VCAP pin.

3: Typical VCAP pin voltage = 1.8V when VDD ≥ VDDMIN.

23.5 Brown-out Reset (BOR)

The Brown-out Reset (BOR) module is based on an internal voltage reference circuit that monitors the regulated supply voltage, VCAP. The main purpose of the BOR module is to generate a device Reset when a brown-out condition occurs. Brown-out conditions are generally caused by glitches on the AC mains (for example, missing portions of the AC cycle waveform due to bad power transmission lines or voltage sags due to excessive current draw when a large inductive load is turned on).

A BOR generates a Reset pulse which resets the device. The BOR selects the clock source based on the device Configuration bit values (FNOSC<2:0> and POSCMD<1:0>).

If an Oscillator mode is selected, the BOR activates the Oscillator Start-up Timer (OST). The system clock is held until OST expires. If the PLL is used, the clock is held until the LOCK bit (OSCCON<5>) is '1'.

Concurrently, the PWRT Time-out (TPWRT) is applied before the internal Reset is released. If TPWRT = 0 and a crystal oscillator is being used, then a nominal delay of TFSCM is applied. The total delay in this case is TFSCM. Refer to Parameter SY35 in Table 26-23 of **Section 26.0 "Electrical Characteristics"** for specific TFSCM values.

The BOR status bit (RCON<1>) is set to indicate that a BOR has occurred. The BOR circuit continues to operate while in Sleep or Idle modes and resets the device should VDD fall below the BOR threshold voltage.

26.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of the dsPIC33EPXXGS50X family electrical characteristics. Additional information will be provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the dsPIC33EPXXGS50X family are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these, or any other conditions above the parameters indicated in the operation listings of this specification, is not implied.

Absolute Maximum Ratings(1)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to V_{SS}(3) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DD} \geq 3.0V$(3) ..... -0.3V to +5.5V
Voltage on any 5V tolerant pin with respect to Vss when $V_{DD} < 3.0V$(3) ..... -0.3V to +3.6V
Maximum current out of V_{SS} pin ..... 300 mA
Maximum current into V_{DD} pin(2) ..... 300 mA
Maximum current sunk/sourced by any 4x I/O pin ..... 15 mA
Maximum current sunk/sourced by any 8x I/O pin ..... 25 mA
Maximum current sunk by all ports(2) ..... 200 mA

Note 1: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those, or any other conditions above those indicated in the operation listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 26-2).

3: See the **“Pin Diagrams”** section for the 5V tolerant pins.

26.1 DC Characteristics

TABLE 26-1: OPERATING MIPS vs. VOLTAGE

Characteristic	VDD Range (in Volts)	Temperature Range (in °C)	Maximum MIPS
			dsPIC33EPXXGS50X Family
—	3.0V to 3.6V(1)	-40°C to +85°C	70
—	3.0V to 3.6V(1)	-40°C to +125°C	60

Note 1: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules (ADC, PGAs and comparators) may have degraded performance. Device functionality is tested but not characterized. Refer to Parameter BO10 in Table 26-13 for the minimum and maximum BOR values.

TABLE 26-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min.	Typ.	Max.	Unit
Industrial Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
Extended Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+140	°C
Operating Ambient Temperature Range	TA	-40	—	+125	°C
Power Dissipation: Internal Chip Power Dissipation: PINT = VDD x (IDD – Σ IOH) I/O Pin Power Dissipation: I/O = Σ ({VDD – VOH} x IOH) + Σ (VOL x IOL)	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ – TA)/θJA			W

TABLE 26-3: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Typ.	Max.	Unit	Notes
Package Thermal Resistance, 64-Pin TQFP 10x10x1 mm	θJA	49.0	—	°C/W	1
Package Thermal Resistance, 48-Pin TQFP 7x7x1.0 mm	θJA	63.0	—	°C/W	1
Package Thermal Resistance, 44-Pin QFN 8x8 mm	θJA	29.0	—	°C/W	1
Package Thermal Resistance, 44-Pin TQFP 10x10x1 mm	θJA	50.0	—	°C/W	1
Package Thermal Resistance, 28-Pin QFN-S 6x6x0.9 mm	θJA	30.0	—	°C/W	1
Package Thermal Resistance, 28-Pin UQFN 6x6x0.5 mm	θJA	26.0	—	°C/W	1
Package Thermal Resistance, 28-Pin SOIC 7.50 mm	θJA	70.0	—	°C/W	1

Note 1: Junction to ambient thermal resistance, Theta-JA (θJA) numbers are achieved by package simulations.

TABLE 26-25: TIMER2 AND TIMER4 (TYPE B TIMER) EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**		**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
TB10	TtxH	TxCK High Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TB15, N = Prescale Value (1, 8, 64, 256)
TB11	TtxL	TxCK Low Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TB15, N = Prescale Value (1, 8, 64, 256)
TB15	TtxP	TxCK Input Period	Synchronous mode	Greater of: 40 or (2 TCY + 40)/N	—	—	ns	N = Prescale Value (1, 8, 64, 256)
TB20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		0.75 TCY + 40	—	1.75 TCY + 40	ns	

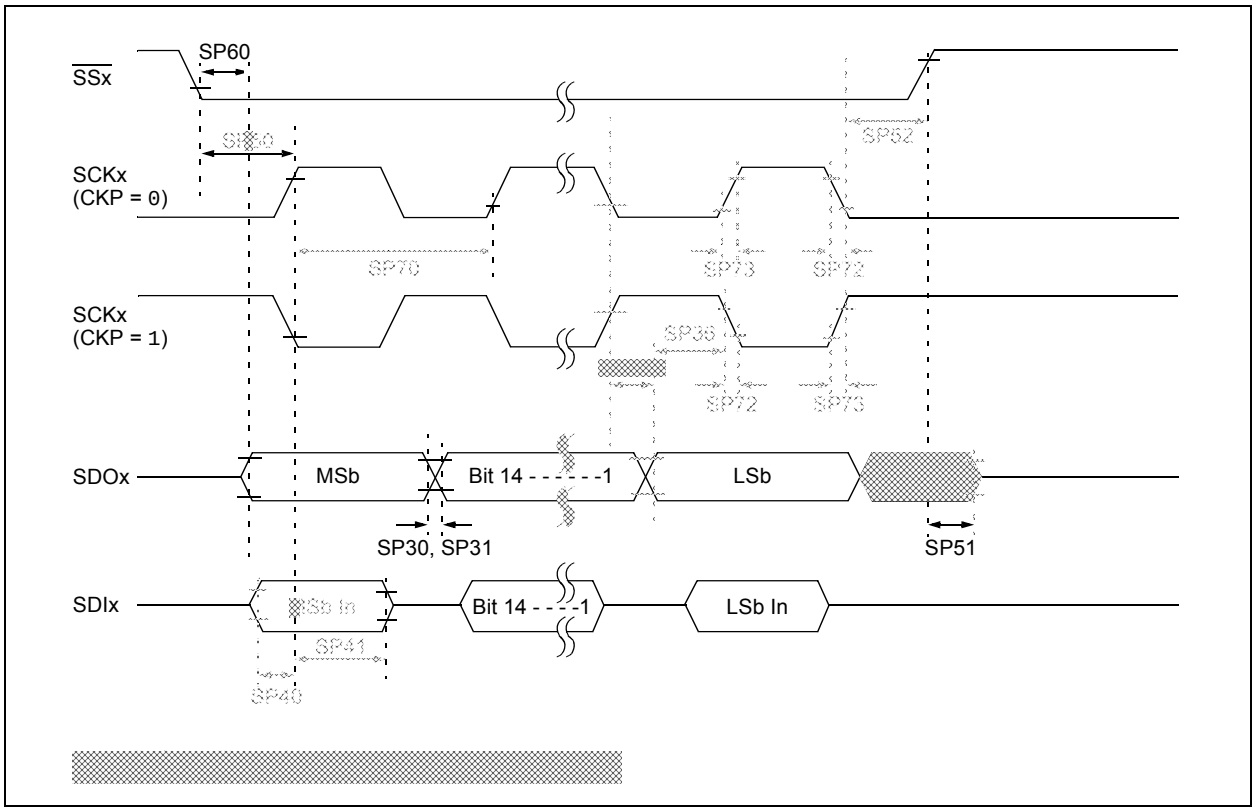
Note 1: These parameters are characterized but not tested in manufacturing.

TABLE 26-26: TIMER3 AND TIMER5 (TYPE C TIMER) EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**		**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
TC10	TtxH	TxCK High Time	Synchronous	TCY + 20	—	—	ns	Must also meet Parameter TC15
TC11	TtxL	TxCK Low Time	Synchronous	TCY + 20	—	—	ns	Must also meet Parameter TC15
TC15	TtxP	TxCK Input Period	Synchronous with Prescaler	2 TCY + 40	—	—	ns	N = Prescale Value (1, 8, 64, 256)
TC20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		0.75 TCY + 40	—	1.75 TCY + 40	ns	

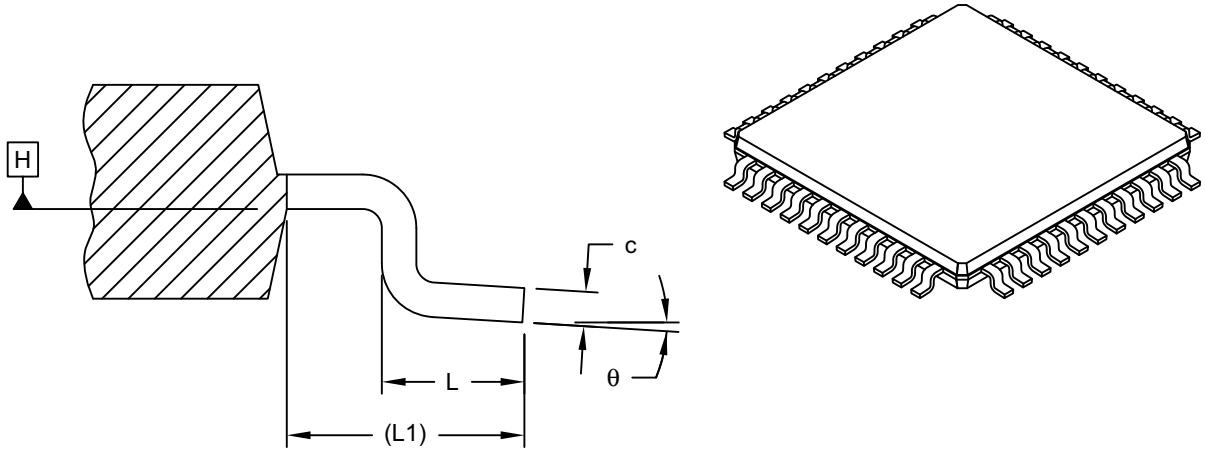
Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 26-16: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING CHARACTERISTICS



44-Lead Plastic Thin Quad Flatpack (PT) - 10x10x1.0 mm Body [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



SECTION A-A

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		44	
Lead Pitch	e		0.80 BSC	
Overall Height	A	-	-	1.20
Standoff	A1	0.05	-	0.15
Molded Package Thickness	A2	0.95	1.00	1.05
Overall Width	E		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Width	b	0.30	0.37	0.45
Lead Thickness	c	0.09	-	0.20
Lead Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	θ	0°	3.5°	7°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Exact shape of each corner is optional.
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

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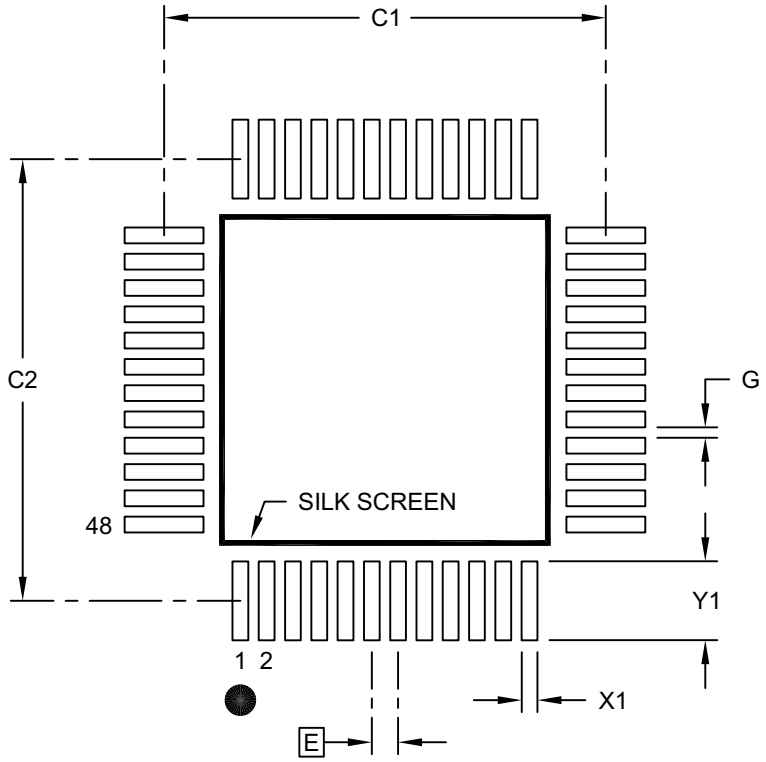
48-Lead Thin Quad Flatpack (Y8) - 7x7x1.0 mm Body [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		8.40	
Contact Pad Spacing	C2		8.40	
Contact Pad Width (X48)	X1			0.30
Contact Pad Length (X48)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-2300-Y8 Rev A

APPENDIX A: REVISION HISTORY

Revision A (June 2013)

This is the initial released version of the document.

Revision B (May 2015)

Adds dsPIC33EPXXGS505 (48-pin) devices to the document:

- Amends the table on page 2 to add the three new devices of this group
- Adds the 48-pin TQFP pin diagram on page 7
- Amends Table 26-3 to include thermal packaging characteristics for 48-pin packages
- Updates **Section 28.1 "Package Marking Information"** to include package marking details for 48-pin TQFP devices
- Updates **Section 28.2 "Package Details"** to include Microchip Drawings C04-183A and C04-2183A (7x7x1.0 mm 48-lead TQFP)

Changes all references to Dual Boot Flash Program Memory throughout the text to "Dual Partition Flash Program Memory". In addition, all accompanying references to "panels" and "Boot modes" are changed to "partitions" and "Partition modes". This includes, but is not limited, to:

- **Section 4.1 "Program Address Space"**
- **Section 5.4 "Dual Partition Flash Configuration"**, and Register 5-1
- **Section 23.10 "Code Protection and CodeGuard™ Security"**, and Table 23-2

Replaces the high-speed pipeline A/D Converter present in pre-production samples with a high-speed, multiple SAR A/D Converter in production devices:

- Replaces **Section 19.0 "High-Speed, 12-Bit Analog-to-Digital Converter (ADC)"** with an entirely new section of the same title, replacing all previous figures and registers
- Updates the summary bullet points under "High-Speed ADC Module" on Page 1 to reflect the feature set of the new module
- Updates Table 4-3 and Table 7-1 to reflect the new module's interrupt structure
- Replaces Table 4-16 with a new register map
- Removes Table 4-16 ("ADC Calibration Register Map"); subsequent tables are renumbered accordingly
- Updates **Section 23.2 "Device Calibration and Identification"** and Table 23-3 to remove the ADCAL registers from the Calibration register table
- Removes all references to the internal temperature sensor, including Table 26-44 (Temperature Sensor Specifications) and Figure 27-11 (Typical Temperature Sensor Voltage vs. Current)

Changes the ESR specification of the V_{CAP} filter capacitor from < 4Ω to < 0.5Ω.

Removes the internal voltage reference in all occurrences. For analog modules, the internal band gap reference is substituted as a replacement source.

Changes the following register names in all occurrences throughout the text:

- "CMPCONx" to "CMPxCON"
- "CMPDACx" to "CMPxDAC"
- "I2CxCON1" to "I2CxCONL"
- "I2CxCON2" to "I2CxCONH"

Updates the text of **Section 5.4.2 "Dual Partition Modes"** to change "Untrusted Dual Panel mode" to "Privileged Dual Partition mode" and clarifies the mode's code security features.

Changes the BSS2 Configuration bit to "BSEN" throughout the text.

Replaces **Section 23.3 "User OTP Memory"** with new text to describe the 64-word User OTP Memory space; also removes Table 23-4.

Amends Table 24-2 with a footnote indicating an increase of instruction execution cycles for most instructions under certain conditions.

Updates the following tables in **Section 26.0 "Electrical Characteristics"** (in addition to changes previously noted):

- Table 26-4, with new specification DC12 (and accompanying footnote)
- Table 26-6, with updated Typical and new Maximum data throughout, and the addition of Parameter DC27 (with accompanying footnote)
- Table 26-7, Table 26-8 and Table 26-10 with updated Typical and Maximum data throughout
- Table 26-9 with updated Typical and Maximum data for Parameters DC61a and DC61b
- Footnotes 6 and 7 of Table 26-11 to clarify the behavior of 5V tolerant pins
- The "ADC Accuracy" specifications of Table 26-43
- Table 26-45 (Table 26-45 in Revision A) with updated specifications for Parameter CM15
- Table 26-46 (Table 26-46 in Revision A) with updated specifications for Parameters DA03 through DA06

Clarifies the text of Footnotes 6 and 7 in Table 26-11 (I/O Pin Input Specifications).

Removes the "Reference Inputs" specifications from Table 26-43 in their entirety.

Replaces Figure 27-5 through Figure 27-10 with new characterization graphs to reflect the most current data and removes "TBD" watermarks.

Updates **Section 28.1 "Package Marking Information"** to reflect the removal of redundant temperature and package code information from all package markings; this is in addition to the new 48-pin package markings previously described.

Other minor typographic corrections throughout the document.